

#	Layer	Thickness	Description	Dk	Df	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
1	Top Side	0.035mm	Starting foil 1/2oz. after plating and processing			
		0.125mm	Prepreg IPC-4101/21	3,5	0,02	FR-4.0
2	Inner Layer 1	0.035mm	ED Base Copper			
		0.200mm	Core IPC-4101/21	4,1	0,02	FR-4.0
3	Inner Layer 2	0.035mm	ED Base Copper			
		0.125mm	Prepreg IPC-4101/21	3,5	0,02	FR-4.0
4	Inner Layer 3	0.035mm	ED Base Copper			
		0.200mm	Core IPC-4101/21	4,1	0,02	FR-4.0
5	Inner Layer 4	0.035mm	ED Base Copper			
		0.125mm	Prepreg IPC-4101/21	3,5	0,02	FR-4.0
6	Bottom Side	0.035mm	Starting foil 1/2oz. after plating and processing			
	Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
Total thickness: 1.015mm						

WÜRTH ELEKTRONIK GmbH
Circuit Board Technology
BASIC6_ML6_1,02_35_V2.12
4_17_V2.12

notes:	BASIC6_ML6_1,02_35_V2.12		
	PCB Thickness Tolerance: ± 10%		
	customer	created	
	pcb name	approved	
Final copper thickness according to IPC-6012	engineer	format	A4, landscape
	date		
Please regard to our sectional design rules: ▶ www.we-online.com	Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen		

